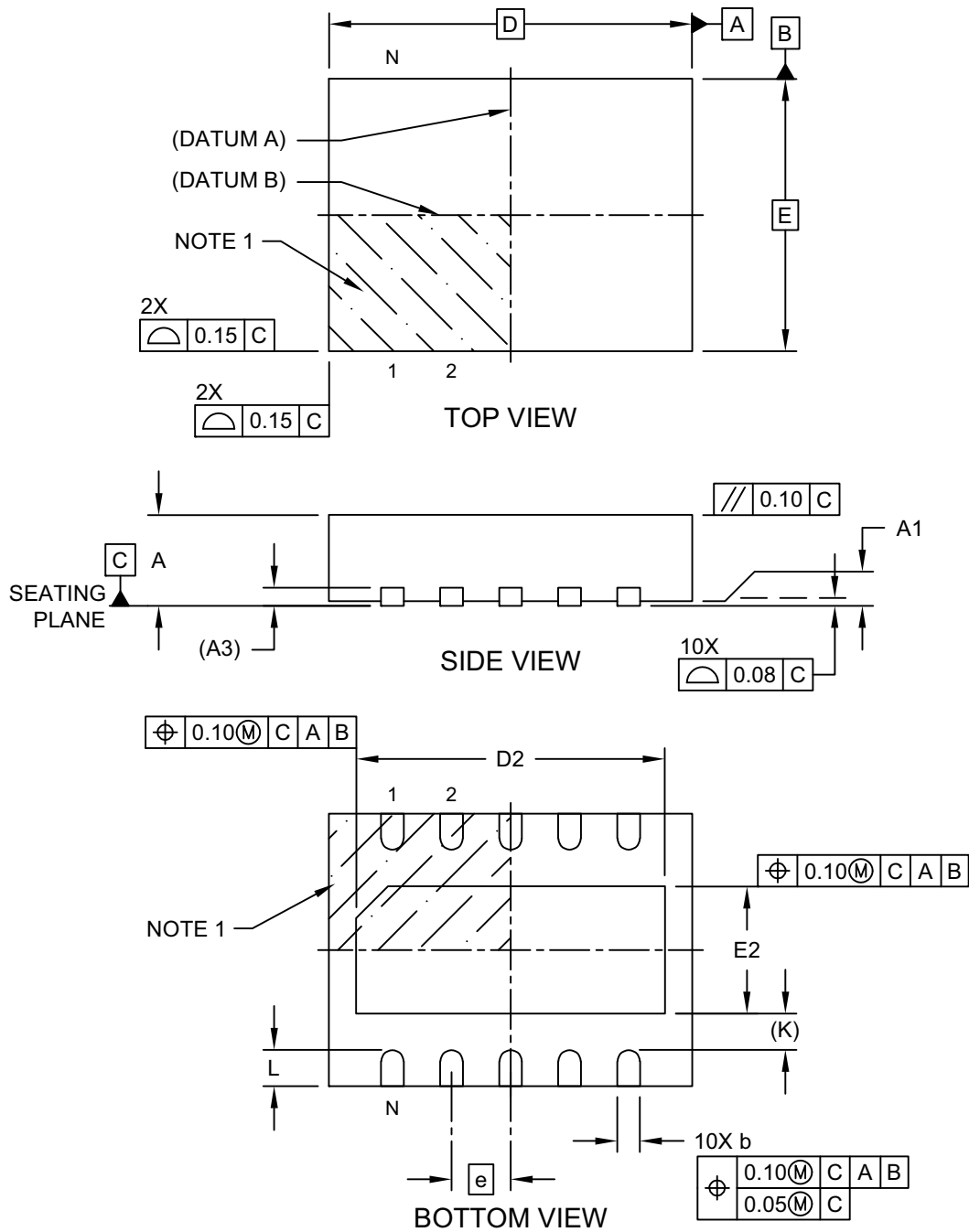


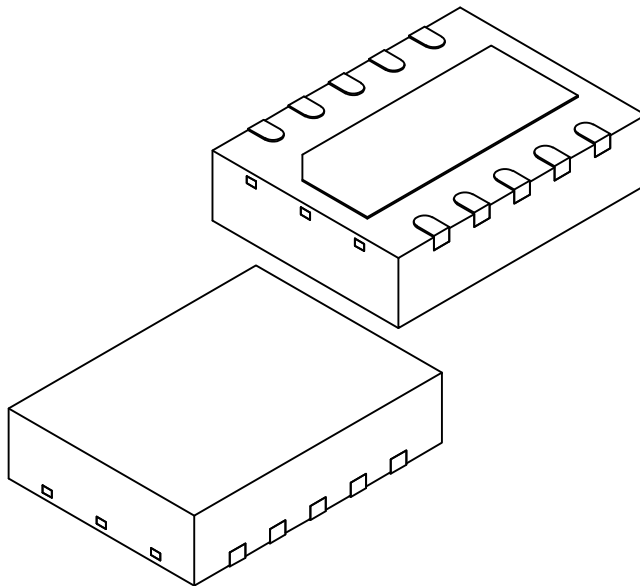
10-Lead Very Thin Plastic Dual Flat, No Lead Package (5XC) - 4x3x1 mm Body [VDFN] With 3.4x1.4 mm Exposed Pad; Microsemi Legacy Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



10-Lead Very Thin Plastic Dual Flat, No Lead Package (5XC) - 4x3x1 mm Body [VDFN] With 3.4x1.4 mm Exposed Pad; Microsemi Legacy Package

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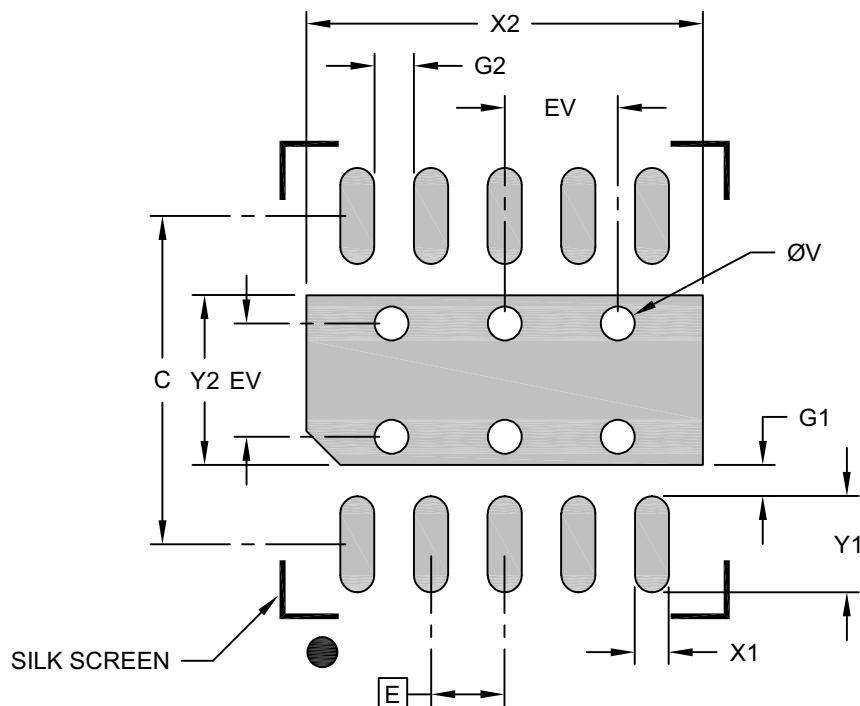
Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	10		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Length	D	4.00 BSC		
Exposed Pad Length	D2	3.30	3.40	3.50
Overall Width	E	3.00 BSC		
Exposed Pad Width	E2	1.30	1.40	1.50
Terminal Width	b	0.18	0.25	0.30
Terminal Length	L	0.30	0.40	0.45
Terminal-to-Exposed-Pad	K	0.40 REF		

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

10-Lead Very Thin Plastic Dual Flat, No Lead Package (5XC) - 4x3x1 mm Body [VDFN] With 3.4x1.4 mm Exposed Pad; Microsemi Legacy Package

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RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Center Pad Width	X2			3.50
Center Pad Length	Y2			1.50
Contact Pad Spacing	C		2.90	
Contact Pad Width (X10)	X1			0.30
Contact Pad Length (X10)	Y1			0.85
Contact Pad to Center Pad (X10)	G1	0.28		
Contact Pad to Contact Pad (X8)	G2	0.35		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-27461 Rev A